

Tyndall National Institute Space Component Analysis

Finbarr Waldron 12th March 2019.





Tyndall National Institute









- Located in Cork, Ireland.
- Micro / Nano Electronics, Photonics & Microsystems
- Ireland's Largest Research Institute
- Excellence in Scientific & Engineering Research.

Tyndall in Numbers





Organisation – Tyndall Research Centres





Highly-differentiated Research Approach



From atoms to systems



5



Tyndall - Key Laboratories & Facilities

- Electronic Packaging & Reliability Analysis:
 - Wire/die bond, flip-chip assembly, DPA, CA, Environmental testing, failure analysis, burn-in, shock & drop, X-ray analysis.
- Electron Microscopy Analysis Facility:
 - (EMAF) SEM, TEM, FIB, EDAX analysis, cryo-stage enabled SEM for biological sample analysis
- IC Design Technology Evaluation (DTE):
 - CA, IC re-engineering, patent infringement, circuit design analysis, analogue, digital & mixed signal diagnostic measurements
- Fabrication Facilities:
 - Silicon CMOS, Compound Semiconductor MEMS, E-beam Lithography, MOVPE materials growth, Training Fab.



IC Circuit, Technology & Construction Analysis



Compound Semiconductor & MEMS Fabrication Facility

Tyndall – Reliability Test Laboratory



Activities:

- Test programme design
- Commercial services
- Support to R&D projects

Facilities:

- Air-to-air thermal shock (X2).
- Temperature cycling (X3).
- Temperature / Humidity (X3).
- High/ Low temperature storage.
- Vacuum storage.
- LDS Shock & Vibration.
- Free Fall Shock Test.
- Salt Spray Test.
- Burn-in Tests
- Seal tests, PIND (hi-rel /space components)







Salt Spray

Vibration





Thermal Shock, Temperature Cycling & Humidity Test

Tyndall – History of Space Activities

- Tyndall working with ESA since 1980's.
- MTSL (Microelectronics Technology Support Laboratory) 1988.
- MTSL helped establish new test facilities at Tyndall:
 - ► *Reliability Test Laboratory.*
 - ► Micro-packaging Analysis Facilities (component CA & DPA)
 - ►Integrated Circuit Test & Analysis.
- Expansion of MTSL in 1991, 1993 & subsequent years.
- Renewal in 1993 & subsequent years (5-year contract).
- Tyndall awarded ISO 17025 Accreditation for Space Component DPA in 2018.
- Development of direct component DPA business with Space industry customers.





Hybrid Microcircuit DPA



CA of IC (FIB cross-section)

ISO17025 Accredited Space Component DPA





Certificate of Registration of Quality Management System to I.S. EN ISO 9001:2015

Tyndall National Institute Lee Maltings Dyke Parade

Cork

NSAI certifies that the aforementioned company has been assessed and deemed to comply with the provisions of the standard referred to above in respect of:-

Research, development and innovation activities in the field of information communications and technology. (ICT).



Approved by: Fergal O'Byrne Head – Business Exceller

Registration Number: 19.2673 Original Registration: 24 December 1997 Last amended on: 12 April 2018 Valid from: 12 April 2018 Remains valid to: 10 April 2021





1

IAF

All valid certifications are listed on NSA/'s website – <u>www.nsal.le</u>. The continued validity of this certificate may be verified under "Certified Company Search"

NSAI (National Standards Authority of Ireland), 1 Swift Square, Northwood, Santry, Dublin 9, Ireland T +353 1 807 3800 E: info@nsat.ip www.nsat.ip



rish WNational Accreditation Board

Accreditation Certificate

University College Cork

Lee Maltings, Prospect Row, Dyke Parade, Cork, Cork

Testing Laboratory

Registration number: 372T

is accredited by the Irish National Accreditation Board (INAB) to undertake testing as detailed in the scope bearing the registration number detailed above, in conformity with ISO/IEC 17025:2005 2nd Edition "General requirements for the competence of testing and calibration laboratories" (This certificate must be read in conjunction with the publicly available scope of accreditation)

> Date of award of accreditation: 13/06/2018 Date of last renewal of accreditation: Expiry date of this certificate of accreditation: 13/06/2023

This accreditation shall remain in force until further notice subject to continuing conformity with the above standard, applicable EA/ILAC requirements and any further requirements specified by the Irish National Accreditation Board.

Manager Chairperson: Dr Adrienne Duff

rson: : <u>Un Kinalian</u> Ms Ita Kinahan

Organisations are subject to annual surveillance and are re-assessed every five years. The renewal dete on this certificate confirms the latest date of renewal of accreditation. To confirm the validity of this certificate, please contact the firsh National Accreditation (Board). NAB is a signatory of the European co-operation (IACA) Mutual Recognition Arrangement (MLA) and the International Laboratory Accreditation Cooperation (IACA) Mutual Recognition Arrangement for Texting.

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ISO 17025 (Tyndall – Space Component DPA)





ISO17025 Accredited Space Component DPA

Scope of Accreditation

- External Visual Inspection Mil-Std-883K, Method 2009.12
- Radiography Mil-Std-883K, Method 2012.9
- Seal Helium Fine Leak Test Mil-Std-883H, Method 1014.13, Condition A1
- Seal Perfluorocarbon Gross Leak Test Mil-Std-883K, Method 1014.13, Cond C1
- PIND (Particle Impact Noise Detection) Test Mil-Std-883K, Method 2020.9, Cond A
- Internal Visual & SEM Inspection Mil-Std-883K, Method 2013.1
- Wire Bond Pull Strength Test Mil-Std-883K, Method 2011.9
- Die Shear Strength Test Mil-Std-883K, Method 2019.9





Internal Visual Inspection



External Visual Inspection





ISO17025 Accredited Space Component DPA

Equipment Highlights

- Keyence VHX 2000 3D Optical Inspection system.
- Nordson-Dage Diamond II XD7600NT X-ray & CT-Scan System
- PTI 4501A PIND Test system
- Leybold Phoenix L300i Helium Leak Detector
- Royce Microtesters (wire bond pull & die shear)
- FEI Nova 650 Nano SEM (EDS)





CT-Scan (Lead-frame Package)

SEM Inspection of Wire Bonds



Nordson-Dage X-ray & CT-scan









ISO17025 Accredited Space Component DPA - Examples





CT-scan of ceramic packaged device



Al wedge / wedge bonds



De-cap of plastic packaged device



Capacitor stack micro-section



Inspection of power ICs in hybrid circuit





RF cable CA



Control IC in hybrid component



CT-scan of isolator component





12

Other Recent Space Component Activities



- Hybrid Microcircuit Construction Analysis.
- Microsystems Component Construction Analysis.
- CCD Construction Analysis.
- Schottky Diode Development.
- Reliability Evaluation of Novel DC-DC Converter Units.
- Thermal & Electrical Simulation of 3D SDRAM Modules.
- Supply of Si Test Structures.
- Characterisation & Supply of RADFET Dosimeters.
- Reverse Engineering of PWM devices.
- GaN Materials Investigations (MMIC).
- PoL DC-DC Converter Evaluation Programme.
- BME Capacitor Evaluation.



CA of point-of-load DC-DC converter (planar magnetics)



CA of relay in TO package

CA of camera unit (CCD)



Summary

Tyndall

- Comprehensive component DPA & CA services.
- Long history working with ESA / ESTEC.
- NDA to assure customer confidentiality.
- Competitive pricing.
- Quick turn-around.
- Tyndall-wide ISO 9001 Quality Management System.
- ISO17025 Accreditation Space Component DPA.
- Happy to facilitate customer visits.



Dr. Franco Ongaro (ESTEC) visiting the Tyndall Component Analysis Laboratory in Nov. 2018. Pictured with Prof. William Scanlon (Tyndall CEO) & Mr. Finbarr Waldron.





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Cesa

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Thank You